

Serial No. 10/797,653  
Amendment dated December 21, 2006  
Office Action dated June 21, 2006

PATENT  
Docket No. 2855/111

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IN THE SPECIFICATION:

DEC 21 2006

Please amend the specification as follows:

Please amend paragraph 0034 as follows:

[0034] Referring to FIG. 6, a cross section of the slider from the recording-medium-facing side is shown. In this cross section, the portion to the left of dividing line 508 is to show the first patch 505a 505b and the portion to the right of dividing line 508 is to show the second patch 505b 505a (coupled together with connector 506). As described above, the main substrate 601 is made of an insulating material. After deposition of the additional conductive material or patch 505a,b and a further insulating film 605, vias are made through insulating film 605 to the conductive patch 505. As described above one of the vias (element 603b 603a) is to connect the conductive patch 505a to the ground pad 507 (via connecting stud 609) and the other via (element 603a 603b) is to connect the conductive patch 505b to the under-shield 515. The vias provide an opening for deposition of conductive material and may be manufactured in any of a variety of ways known in the art. Once the vias are in place, the under-shield 515 and connecting stud 609 are formed on top of them (e.g., through a mask and deposition process)(see block 325 in FIG. 3b). In this embodiment, the under shield and the connecting stud are formed in a manner similar to the conductive patch 505a,b as described above.